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Docket No.: M4065.0127/P127-A  
(PATENT)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Kie Y. Ahn, et al.

Application No.: 09/660,324

Group Art Unit: 2581

Filed: September 12, 2000

Examiner: F. Toledo

For: SILICON MULTI-CHIP MODULE  
PACKAGING WITH INTEGRATED  
PASSIVE COMPONENTS AND METHOD  
OF MAKING

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AMENDMENT

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated September 19, 2002 (Paper No. 14),  
please amend the above-identified U.S. Patent application as follows:

In the Claims

Please replace claim 88 with the following. Please cancel claims 90 and 91.

88 (amended) A process for forming an interposer element for use as a chip  
carrier comprising the steps of:

providing an insulating layer on at least one surface of a silicon substrate and

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